International
IOR Rectifier

ADVANCE INFORMATION **Data Sheet No. PD60186**

IR2170

OVER CURRENT SENSING IC

Features

- Floating channel up to +600V
- Monolithic integration
- Overcurrent sensing through shunt resistor
- Low I_{QBS} allows the boot strap power supply
- Independent fast overcurrent trip signal
- High common mode noise immunity
- Input overvoltage protection for IGBT short circuit condition
- Open Drain outputs

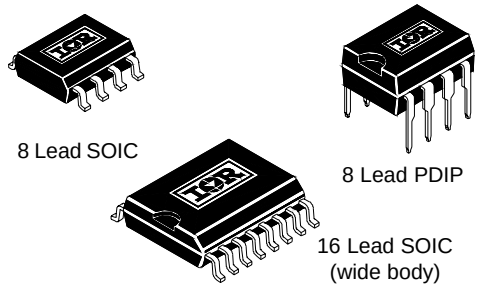
Product Summary

V_{OFFSET}	600Vmax
I_{QBS}	1mA
Overcurrent trip signal delay	1.5usec (typ)
Overcurrent trip level	+/-260mV (typ.)

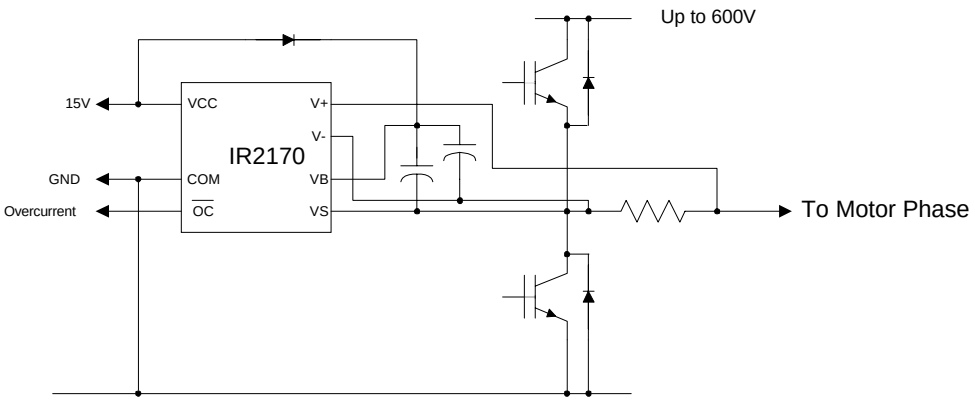
Description

IR2170 is the monolithic over current sensing IC designed for motor drive applications. It senses the motor phase current through an external shunt resistor, detects overcurrent condition, and transfers the signal to the low side. IR's proprietary high voltage isolation technology is implemented to enable the high bandwidth signal processing. The dedicated overcurrent trip ($\overline{OC}$) signal facilitates IGBT short circuit protection. The OC output pulse width can be programmed by the external resistor and capacitor. The open-drain outputs make easy for any interface from 3.3V to 15V.

Packages



Block Diagram



Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM, all currents are defined positive into any lead. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition		Min.	Max.	Units
V_S	High side offset voltage		-0.3	600	V
V_{BS}	High side floating supply voltage		-0.3	25	
V_{CC}	Low side and logic fixed supply voltage		-0.3	25	
V_{IN}	Maximum input voltage between V_{IN+} and V_{IN-}		-5	5	
V_{OC}	Overcurrent output voltage		COM -0.3	VCC +0.3	
V_{IN-}	V_{IN-} input voltage (note 1)		V_S -5	V_{B+} 0.3	
dV/dt	Allowable offset voltage slew rate		—	50	V/ns
P_D	Package power dissipation @ $T_A \leq +25°C$	8 lead SOIC	—	.625	W
		8 lead PDIP	—	1.0	
		16 lead SOIC	—	1.25	
Rth_{JA}	Thermal resistance, junction to ambient	8 lead SOIC	—	200	°C/W
		8 lead PDIP	—	125	
		16 lead SOIC	—	100	
T_J	Junction temperature		—	150	°C
T_S	Storage temperature		-55	150	
T_L	Lead temperature (soldering, 10 seconds)		—	300	

Note 1: Capacitors are required between V_B and Vin-, and between V_B and Vs pins when bootstrap power is used. The external power supply, when used, is required between Vs and Vin-, and between V_B and Vs pins.

Recommended Operating Conditions

The output logic timing diagram is shown in figure 1. For proper operation the device should be used within the recommended conditions.

Symbol	Definition	Min.	Max.	Units
V_B	High side floating supply voltage	V_S +13.0	V_S +20	V
V_S	High side floating supply offset voltage	note 2	600	
V_{OC}	Overcurrent output voltage	COM	VCC	
V_{CC}	Low side and logic fixed supply voltage	9.5	20	
V_{IN}	Input voltage between V_{IN+} and V_{IN-}	-260	+260	mV
T_A	Ambient temperature	-40	125	°C

Note 2: Logic operation for Vs of -5 to +600V. Logic state held for Vs of -5V to -V_{BS}.

DC Electrical Characteristics

V_{CC} = V_{BS} = 15V, unless otherwise specified.

Symbol	Definition	Min.	Typ.	Max.	Units	Test Conditions
V_{OC+}	Overcurrent trip positive input voltage	—	260	—	mV	
V_{OC-}	Overcurrent trip negative input voltage	—	-260	—		
I_{LK}	Offset supply leakage current	—	—	50	µA	$V_B = V_S$ = 600V
I_{QBS}	Quiescent V_{BS} supply current	—	1	2	mA	V_S = 0V
I_{QCC}	Quiescent V_{CC} supply current	—	—	1		
I_{OCC}	OC output sink current	10	—	—		V_O = 1V
		1	—	—		V_O = 0.1V

AC Electrical Characteristics cont.

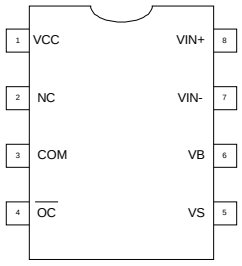
V_{CC} = V_{BS} = 15V, unless otherwise specified.

Symbol	Definition	Min.	Typ.	Max.	Units	Test Conditions
Proagation delay characteristics						
tdoc	Propagation delay time of OC	1	1.5	—	µsec	
twoc	Low true pulse width of OC	—	1	—		

Lead Definitions

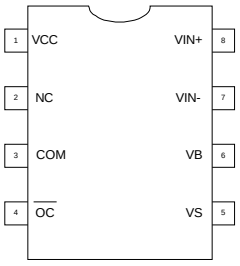
Symbol	Description
V_{CC}	Low side and logic supply voltage
COM	Low side logic ground
V_{IN+}	Positive sense input
V_{IN-}	Negative sense input
V_B	High side supply
V_S	High side return
$\overline{OC}$	Overcurrent output (negative logic)
N.C.	No connection

Lead Assignments



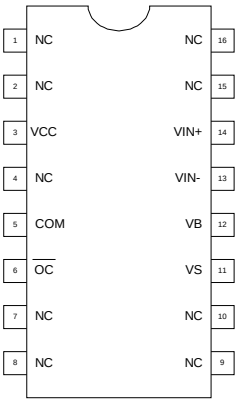
8 lead SOIC

IR2170S



8 lead PDIP

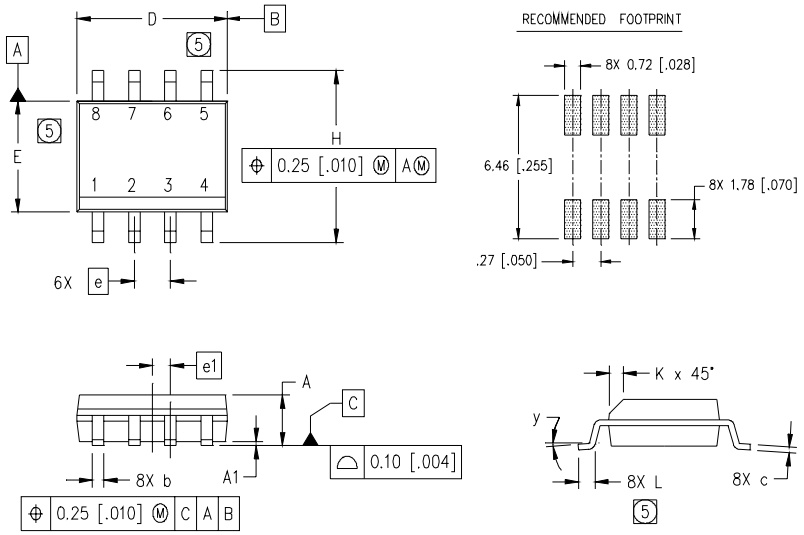
IR2170



16 lead SOIC

IR21706S

Case Outline - 8 Lead SOIC



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.014	.018	0.36	0.46
c	.0075	.0098	0.19	0.25
D	.189	.196	4.80	4.98
E	.150	.157	3.81	3.99
e	.050 BASIC		1.27 BASIC	
e 1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.011	.019	0.28	0.48
L	.016	.050	0.41	1.27
y	0°	8°	0°	8°

NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M–1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS–012AA.

5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [.006].
6. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

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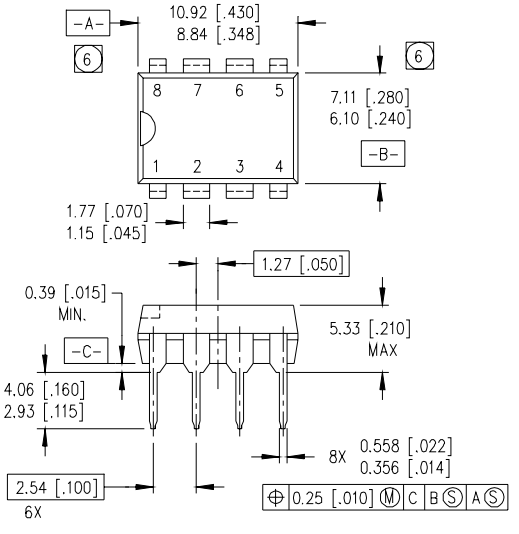
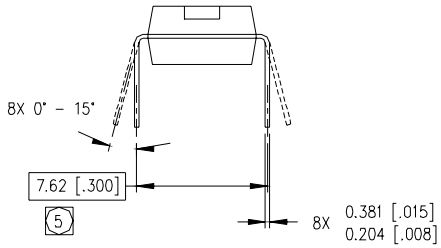


NOTES:

1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M–1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS–001AB.

5. MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM PLANE C.
6. DIMENSION DOES NOT INCLUDE MOLD PROTUSIONS. MOLD PROTUSIONS SHALL NOT EXCEED 0.25 [.010].



8 Lead PDIP

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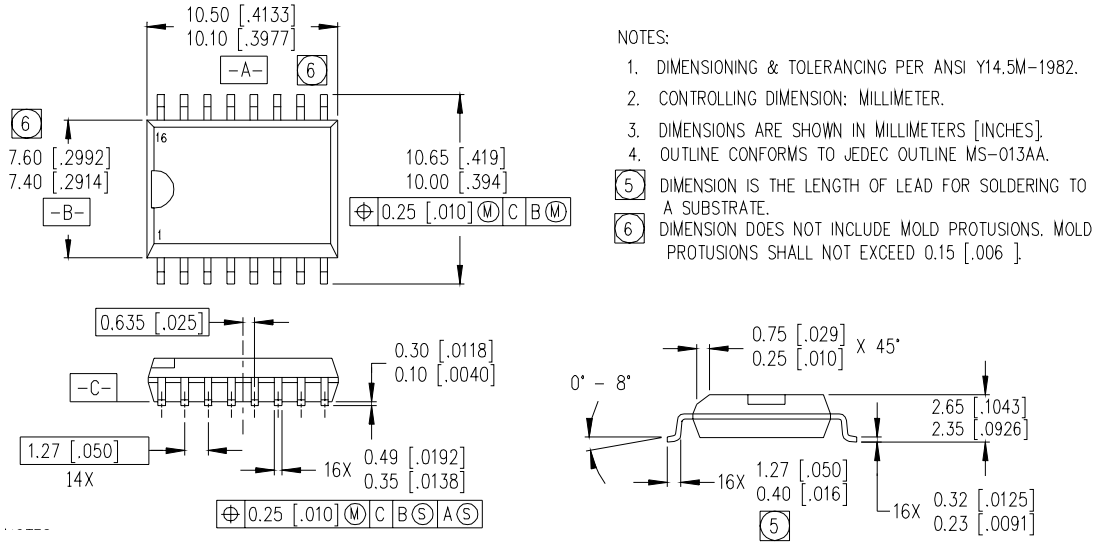

16 Lead SOIC (wide body)

01-3014
03

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